

The Big Deal

- Patented design eliminates in band spurs
- Pass band cut-off up to 21 GHz
- Stop band up to 35 GHz
- Excellent repeatability through IPD* process



Available in Low Pass, High Pass and Band Pass designs

Product Overview

Mini-Circuits' *X-Series* reflectionless filters employs a novel filter topology which absorbs and terminates stop band signals internally rather than reflecting them back to the source. This new capability enables unique applications for filter circuits beyond those suited to traditional approaches. Traditional filters are reflective in the stop band, sending signals back to the source at 100% of the power level which interact with neighboring components and often result in intermodulation and other interferences. Reflectionless filters eliminate stop band reflections, allowing them to be paired with sensitive devices and used in applications that otherwise require circuits such as isolation amplifiers or attenuators.

Key Features	Advantages
Easy integration with sensitive reflective components, e.g. mixers, multipliers	Reflectionless filters absorb unwanted signals, preventing reflections back to the source. This reduces generation of additional unwanted signals without the need for extra components like attenuators, improving system dynamic range and saving board space.
Enables stable integration of wideband amplifiers	Because reflectionless filters maintain good impedance in the stop band; they can be integrated with high gain, wideband amplifiers without the risk of creating instabilities in these out of band regions.
Cascadable	Reflectionless filters can be cascaded in multiple sections to provide sharper and higher attenuation, while also preventing any standing waves that could affect pass band signals.
Excellent power handling in a tiny surface mount device	High power handling extends the usability of these filters to the transmit path for inter-stage filtering.
Small size, 3x3mm QFN	Allows replacement of filter/attenuator pairs with a single reflectionless filter, sav- ing board space.
Excellent repeatability of RF performance	Through semiconductor IPD process, X-series filters are inherently repeatable for large volume production.
Excellent stability over temperature	With ± 0.3 dB variation over temperature ideal for use in wide temperature range applications without the need for additional temperature compensation.
Operating temperature up to 105°C	Suitable for operation close to high power components.

*IPD - Integrated Passive Device, is a GaAs semiconductor process

Reflectionless Bandpass Filter

50Ω 2350 to 3150 MHz

Features

- \bullet Match to 50 $\!\Omega$ in the stop band, eliminates undesired reflections
- Cascadable
- Excellent Power handling
- Temperature stable, up to 105°C
- Small size, 3 x 3 mm
- Protected by US Patent No. 8,392,495

Applications

- Wi-Fi
- WiMax
- Bluetooth
- Satellite

General Description

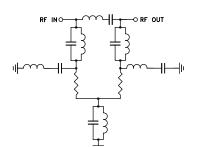
 Available Tape and Reel at no extra cost

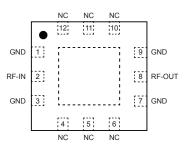
 Reel Size
 Devices/Reel

 7"
 20, 50, 100, 200, 500, 1000, 2000

Mini-Circuits' XBF-282+ reflectionless filter employs a novel filter topology which absorbs and terminates stop band signals internally rather than reflecting them back to the source. This new capability enables unique applications for filter circuits beyond those suited to traditional approaches. Traditional filters are reflective in the stop band, sending signals back to the source at 100% of the power level. These reflections interact with neighboring components and often result in inter-modulation and other interferences. Reflectionless filters eliminate stop band reflections, allowing them to be paired with sensitive devices and used in applications that otherwise require circuits such as isolation amplifiers or attenuators.

simplified schematic and pad description





Function	Pad Number	Description
RF-IN	2	RF Input Pad
RF-OUT	8	RF Output Pad
GND	1,3,7,9, Paddle	Connected to ground
NC (GND Externally)	4,5,6,10,11,12	No internal connection



+RoHS Compliant The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

XBF-282+

Electrical Specifications¹ at 25°C

Param	eter	F#	Frequency (MHz)	Min.	Тур.	Max.	Unit
Deep Band	Insertion Loss	F2-F3	2350 - 3150	—	3.2	3.6	dB
Pass Band	VSWR	F2-F3	2350 - 3150	—	1.2	—	:1
Stop Band, Lower	Rejection	DC-F1	DC - 1810	12	15	_	dB
Stop Band, Lower	VSWR	DC-F1	DC - 1810	—	1.2	—	:1
	Rejection	F4-F5	3800 - 9500	12	15	_	dB
Stop Band, Upper	Пејесноп	F5-F6	9500 - 20000	_	20	_	db
	VSWR	F4-F5	3800 - 9500	_	1.2	_	:1
	VOWIT	F5-F6	9500 - 20000	—	1.5	—	

¹ Measured on Mini-Circuits Characterization Test Board TB-844-282B+

Absolute Maximum Ratings⁴

Parameter	Ratings
Operating Temperature	-55°C to +105°C
Storage Temperature	-65°C to +150°C
RF Power Input, Passband (F2-F3) ²	2W at 25°C
RF Power Input, Stopband (DC-F2, F3-F6) ³	0.5W at 25°C

 $^{\scriptscriptstyle 2}$ Passband rating derates linearly to 1W at 105°C ambient

 $^{\rm 3}$ Stopband rating derates linearly to 0.25W at 105°C ambient

⁴ Permanent damage may occur if any of these limits are exceeded.

ESD rating

Human body model (HBM): Class 2(2000 to <4000 V) in accordance with ANSI/ESD 5.1-2001

MSL rating

Moisture Sensitivity: MSL1 in accordance with IPC/JEDEC J-STD-020D

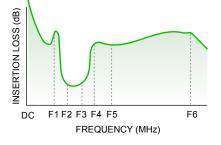
Frequency (MHz) Insertion Loss VSWR (dB) (:1) 10 44.12 1.04 50 100 1.04 1.05 39.26 35.00 200 29.51 1.07 400 23.66 1.11 1000 16.34 1.26 1.23 1810 16.16 2350 2.50 1.20 3150 3800 3.10 15.35 1.04 1.25 5000 1.19 15.22 6500 17.66 1.10 8000 9500 19.49 17.03 1.10 1.34 11000 20.26 1.29 13000 22.61 1.37 15000 20.73 1.40 17000 1.28 18.99 19000 18.32 1.82 20000 18.66 2.59 XBF-282+ INSERTION LOSS XBF-282+ VSWR 50 3.0 2.5 VSWR 2.0 1.5 0 1.0 4000 8000 12000 20000 0 4000 8000 12000 16000 20000 0 16000 FREQUENCY (MHz) FREQUENCY (MHz)

Typical Performance Data at 25°C

lMini-Circuits

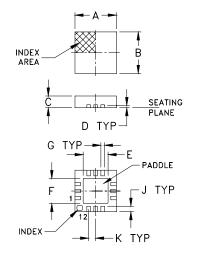
www.minicircuits.com P.O. Box 350166, Brooklyn, NY 11235-0003 (718) 934-4500 sales@minicircuits.com

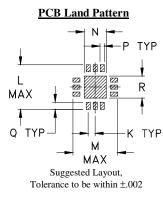
Specification Definition



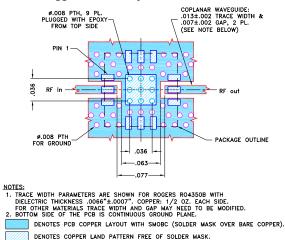


Outline Drawing





Demo Board MCL P/N: TB-844-282B+ (without connectors) TB-844-282BC+ (with connectors) B20-118-F1+ Connector sold separately Suggested PCB Layout: PL-451+



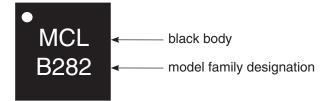
Outline Dimensions (inch)

J	н	G	F	E	D	С	В	А
.016		.009	.057	.057	.008	.035	.118	.118
0.41		0.23	1.45	1.45	0.20	0.89	3.00	3.00
wt		R	Q	Р	Ν	М	L	К
grams		.049	.020	.010	.049	.127	.127	.020
0.02		1.24	0.51	0.25	1.24	3.23	3.23	0.51

Tape & Reel Packaging

DEVICE ORIENTATION IN T&R

Product Marking



DIRECTION	OF	FEED

Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices per Reel see note		
8	4	7	Small quantity standard	20 50 100 200 500	
		7	Standard	1000, 2000	

